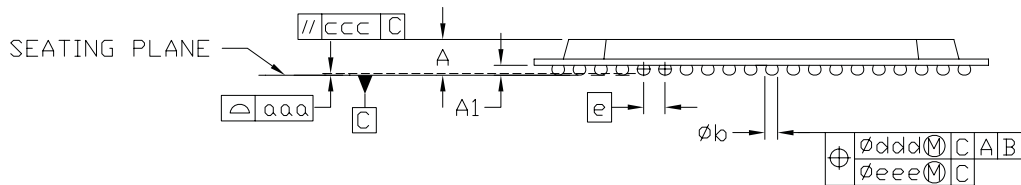
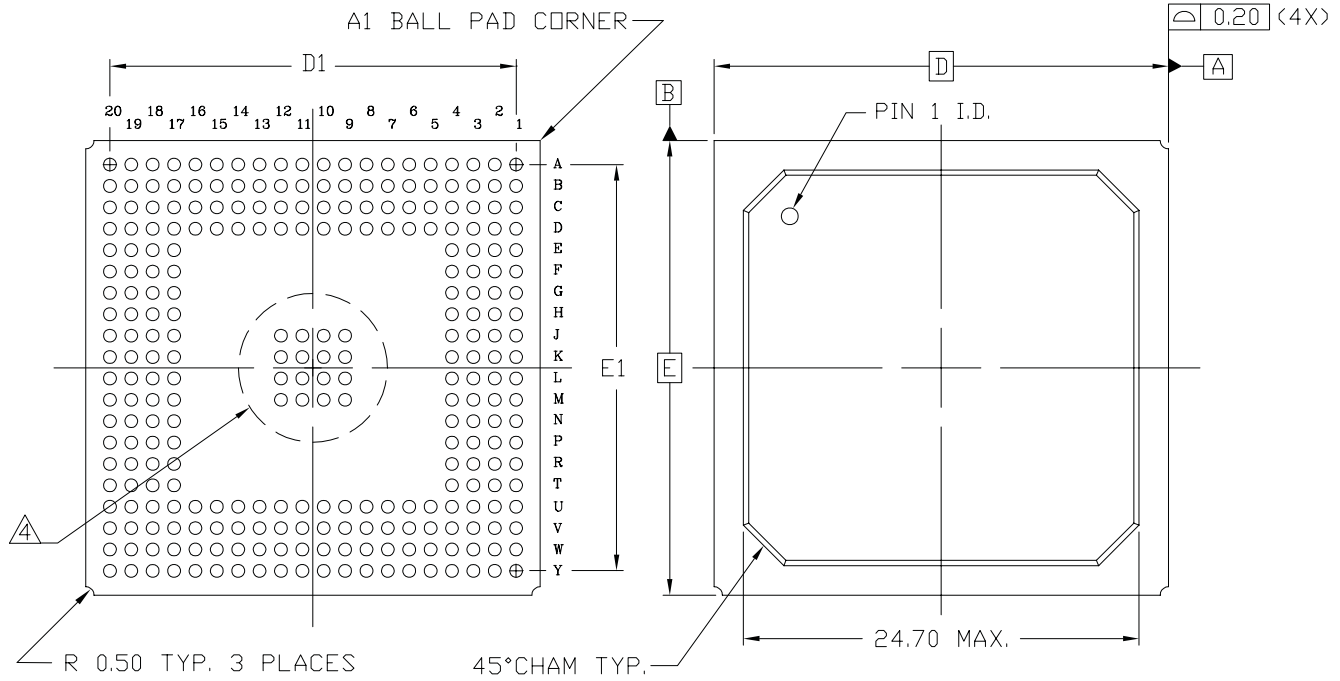


BOTTOM VIEW

TOP VIEW



BG256 - 63/37 (Sn/Pb) Solder Balls
 BGG256 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	\approx	2.30	2.55
A ₁	0.50	0.60	0.70
D/E	27.00 BSC		
D ₁ /E ₁	24.14 REF		
e	1.27 BSC		
ϕ_b	0.60	0.75	0.90
aaa	\approx	\approx	0.20
ccc	\approx	\approx	0.35
ddd	\approx	\approx	0.30
eee	\approx	\approx	0.15
M	20		

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
 - SYMBOL 'M' IS THE BALL MATRIX SIZE.
 - CONFORMS TO JEDEC MS-034-BAL-2
- \triangle 16 EXTRA BALLS (GROUNDED) - APPLICABLE TO DEVICES WITH 28K LOGIC GATES OR MORE, OR 50K SYSTEM GATES OR MORE.

256-BALL PLASTIC BGA (BG256/BGG256)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
4/06/01	1.1	Initial Xilinx release.
4/13/06	1.2	Updated to include PB-free package.
3/19/07	1.3	Updated Note 4 to reflect the equivalent system gates.